

IN THE SPECIFICATION

Please replace the original title with the replacement titled provided below:

“SELF-PINNED ABUTTED JUNCTION HEADS HAVING AN ARRANGEMENT OF  
A SECOND HARD BIAS LAYER AND A FREE LAYER FOR PROVIDING A NET  
NET LONGITUDINAL BIAS ON THE FREE LAYER”

Delete the paragraph beginning at page 6, line 11:

A method for forming self-pinned abutted junction heads according to an embodiment of the present invention includes forming a free layer, forming first hard bias layers abutting the free layer and forming second hard bias layers over the first hard bias layers discontiguous from the free layer, the second hard bias layers being anti-parallel to the first hard bias layers, the first and second hard bias layers providing a net longitudinal bias on the free layer.

Replace the paragraph beginning at page 6, line 11 with the following replacement paragraph.

Fig. 6a illustrates a self-pinned abutted junction head structure 600a prior to forming a hard bias/lead layer according to an embodiment of the present invention. As discussed in Fig. 5, a first film 610 may be deposited as a buffer layer onto a substrate 620, such as glass. However, the present invention is not limited to this substrate, for example, the substrate could also be semiconductor material or a ceramic material such as used for conventional sliders. A self pinned-layer 630 is formed on the buffer layer 610. The self-pinned layer has a first end 634, a second end 635 and a central region 636. A spacer layer 640, such as copper (Cu), may then be deposited onto the self pinned-layer 630. However, the present invention is not limited to Cu as a spacer layer 640. Next, as discussed in Fig. 5, a free layer 650 is formed on the spacer layer 640 and a capping layer 660 may be formed on the free layer 650.